


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A		17 JUL 24	X

HOLE TOLERANCE
UNLESS SPECIFIED
PLATED: +/- 3 MILS
NON PLATED: +/- 2 MIL

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
□	6.0	PLATED	66	
●	9.99	PLATED	551	
◆	40.0	PLATED	18	
△	100.0	PLATED	15	
⊙	191.0	PLATED	2	
⊖	213.0	PLATED	4	
⊗	118.0	NON-PLATED	4	
⊠	185.0	NON-PLATED	4	

TOTAL HOLES: 664

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS FRACTIONS Holes .XX +/- .005 .XX +/- .010 .XX +/- .020 .0000 +/- .0000	APPROVAL	DATE					
	DAVIDE D'AMICO	19AUG20					
	BILLY PHILLIPS	19AUG20					
	BOB MACDONALD	19AUG20					
	DAVE WILLIAMS	19AUG20					
MATERIAL	ADOT ENGINEERING ADOT LIBRARY	19AUG20	TITLE FABRICATION EVAL-LTC7892-BZ				
UNWARRANTED RELEASE		caddbby7					
FINISH	FOR DESIGNER	29JUN22	SIZE	FSCH NO	DRAWING NUMBER	REV	
	Rechtel L.	600000	D	2435509	-074836	A	
	FOR MANAGER	600000					
	DESIGNER	600000					
	X	caddbby7					
DO NOT SCALE DWG	SCALE		1/1	SHEET		1 OF 2	

8

7

6

5

4

3

2

1

REVISIONS			
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NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).
ALL DOCUMENTS & SPECIFICATIONS REFERRED TO BELOW SHOULD BE THE LATEST REVISIONS.

MATERIAL: HOMOGENEOUS MATERIALS IN THIS BOARD SHALL BE COMPLAINT WITH THE EU DIRECTIVE 2002/95/EC

2. BOARD MATERIAL (USE CHECKED ITEMS)
(X) ISOLA 370HR OR S1000-2 OR IT180 OR EQUIVALENT
() ISOLA-FR408HR OR EQUIVALENT
() ISOLA I5410
() MEGTRON 6
() NELCO-4000-13
() ROGERS 4350B
() ROGERS 3003
() ARLOH 85N
() EN370D
() OTHER _____
3. ALL LAMINATES & BONDING MATERIALS SHOULD BE SELECTED FROM IPC-4101 OR IPC-4103. (TG>170 DEG C TD>300 DEG C)
UL FLAMMABILITY RATING 94V-0. BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796/UL796F.
4. REFER TO IPC-6010 SERIES, CLASS 2 FOR FABRICATION. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2.
5. REFER TO LAMINATION DIAGRAM FOR OVERALL BOARD THICKNESS, TOLERANCE APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES. FINISHED THICKNESS MEASURED FROM TOP COPPER TO BOTTOM COPPER.
6. BOW & TWIST NOT TO EXCEED 0.0075 INCHES (0.75%) PER LINEAR INCH AND SHOULD BE MEASURED PER IPC-TM-650, METHOD 2.4.22.
7. ACCEPTABILITY PER ADI SPECIFICATION TST00115.

TOOLING:

8. IMPEDANCE REQUIREMENTS: IF NO STACKUP IS DEFINED, THE VENDOR IS ALLOWED TO ADJUST THE DIELECTRIC THICKNESS & TRACE WIDTHS TO MEET THE IMPEDANCE REQUIREMENT. IF SPECIFIED, THE VENDOR MUST MEET THE REQUIREMENTS LISTED IN THE IMPEDANCE TABLE. ANY ADJUSTMENT MADE TO THE DEFINED STACKUP, TRACE WIDTH & SPACING THAT IMPACT THE REQUIREMENTS MUST HAVE WRITTEN APPROVAL FROM ADI.

9. FILLET OPTIONS TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS.
() FILLETS ALLOWED
(X) FILLETS NOT ALLOWED

10. THEIVING:
() VENDOR MAY ADD THEIVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS MAINTAINING A MINIMUM 0.100 INCH CLEARANCE FROM ALL COPPER FEATURES.
(X) VENDOR MAY NOT ADD THEIVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS.

11. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003 INCHES.

FINISH:

12. DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN 0.005 INCHES DTP UNLESS SPECIFIED. MINIMUM BARREL PLATING OF 0.001 INCHES. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO HINDER PROPER SOLDER WICKING. BARREL RELIEF ON SOLDERMASK ALLOWED IN UNFILLED VIA IN PAD HOLES.

13. PLATING SPECIFICATION:
(X) REFER TO LAMINATION DIAGRAM FOR FINISHED COPPER WEIGHT/THICKNESS REQUIREMENTS
THE STARTING COPPER WEIGHT/THICKNESS CAN VARY AS LONG AS THE FINISHED COPPER WEIGHT/THICKNESS IS NOT LESS THAN THE SPECIFIED VALUE.

14. SURFACE FINISH:
(X) IMMERSION GOLD (ENIG) 1.58-3.94 MICRO INCHES OVER 118-236 MICRO INCHES MIN. OF ELECTROLESS NICKEL PER IPC-4552
() OSP (ORGANIC SOLDERABILITY PRESERVATIVE)
() IMMERSION SILVER
() SOFT WIRE BONDABLE GOLD 30-50 MICRO INCHES OF SOFT WIRE
BONDABLE GOLD OVER 100-150 MICRO INCHES OF NICKEL
() EDGE CONNECT FINGERS ARE TO BE PLATED WITH 100 MICRO-INCHES (.0001") OF LOW STRESS NICKEL UNDER 30 MICRO-INCHES (.0003") OF GOLD
() OTHER _____

15. SOLDERMASK:
SOLDERMASK OVER BARE COPPER OR BARE GOLD (BOTH SIDES) TO MEET IPC-SM-840.
IF PRESENT, DO NOT MODIFY SOLDERMASK DEFINED PADS (MASK OPENINGS LESS THAN COPPER PAD) WITHOUT APPROVAL.
(X) LPI
() OTHER _____

- COLOR
(X) GREEN
() OTHER _____

16. APPLY SILKSCREEN TO BOTH SIDES USING A NON-CONDUCTIVE, EPOXY BASED INK PER ARTWORK.
(X) WHITE
() OTHER _____

TESTING:

17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE.
THE PCB SHALL HAVE A VERIFICATION STAMP.

18. A TIME DOMAIN REFLECTOMETER REPORT (TDR) FOR EACH IMPEDANCE CONTROLLED LAYER & A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT. INSTANCES WHERE TDR TESTING CAN'T BE PERFORMED BECAUSE THE TRACE LENGTH IS TOO SHORT ON THE OUTER LAYERS AT THE PIN ESCAPES IS ACCEPTABLE. ALL OTHER INSTANCES MUST BE REPORTED.

MISCELLANEOUS:

19. IF PRESENT, ALL BLIND/BURIED VIAS WITH AN ASPECT RATIO <1:1 TO BE PLATED SHUT WITH COPPER WHEN USED AS VIA-IN-PAD OR AS A STACKED VIA. BLIND/BURIED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED WITH NON-CONDUCTIVE EPOXY.

20. FOR VIA FILL INFORMATION REFER TO DRILL CHART:
(X) NON-CONDUCTIVE EPOXY FILL ALL LESS THAN 0.010 INCHES DRILLED VIAS
() COPPER FILL ALL 0.XXXX INCHES DRILLED VIAS

21. INTENTIONAL SHORTS:
IF AN INTENTIONAL SHORT REPORT IS SUPPLIED AND DOES NOT MATCH THE FAB DATA THEN ADI APPROVAL IS REQUIRED.

22. PEMNUTS:
() PEMNUTS TO BE INSTALLED BY FABRICATOR
() PEMNUTS NOT TO BE INSTALLED BY FABRICATOR
(X) NOT APPLICABLE


23. MANUFACTURER TO ETCH/STAMP WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE UNLESS OTHERWISE SPECIFIED:
A. UL CODE-FLAMMABILITY RATING FOR THOSE APPROVED MATERIALS (IF APPLICABLE)
B. DATE CODE
C. LOT NUMBER
D. MANUFACTURER LOGO

25. PANELIZATION:
BOARDS TO BE SHIPPED IN ARRAY AND KEPT INTACT
PANEL TO BE SUBJECTED TO CUSTOMERS APPROVAL
PANEL SOLDER PASTE STENCIL GERBER TO BE PROVIDED TO ANALOG

27. MINIMUM DESIGN LINE WIDTH IS .008 INCH.
28. MINIMUM DESIGN LINE SPACING IS .008 INCH.

FOR NOTES REVISIONS, SEE NUMBER 2002

LAMINATION DIAGRAM				
LAYER NUMBER	LAYER NAME	COPPER THICKNESS (OZ, INCH)	DIELECTRIC THICKNESS (INCH)	MATERIALS
1	TOP	2 OZ, 0.0028"		FINAL CU/THICKNESS AFTER PLATING
			0.006	ISOLA 370HR/EQUIVALENT
2	LAYER_2	2 OZ, 0.0028"		CU CLAD
			0.010	ISOLA 370HR/EQUIVALENT
3	LAYER_3	2 OZ, 0.0028"		CU CLAD
			THIN AS REQ'D	ISOLA 370HR/EQUIVALENT
4	LAYER_4	2 OZ, 0.0028"		CU CLAD
			0.010	ISOLA 370HR/EQUIVALENT
5	LAYER_5	2 OZ, 0.0028"		CU CLAD
			0.006	ISOLA 370HR/EQUIVALENT
6	BOTTOM	2 OZ, 0.0028"		FINAL CU/THICKNESS AFTER PLATING
THE FINISHED PCB THICKNESS TO BE:		0.062" +/-10%		

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS FRACTIONS HOLE INCHES .001 .005 .010 .015 .020 .030 .040 .050 .060 .070 .080 .090 .100 .125 .150 .175 .200 .250 .300 .350 .400 .450 .500 .600 .700 .800 .900 1.000 1.250 1.500 1.750 2.000 2.500 3.000 3.500 4.000 4.500 5.000 6.000 7.000 8.000 9.000 10.000 MATERIAL	APPROVAL		DATE		TITLE FABRICATION EVAL-LTC7892-BZ
	SPECIFIED BY BILLY PHILLIPS DESIGNED BY BOB MACDONALD CHECKED BY DAVE WILLIAMS APPROVED BY ADOT LIBRARY		19AUG20 19AUG20 19AUG20 19AUG20 19AUG20		
FINISH	FOR DESIGNER Rechtel, L. FOR MANAGER X DESIGNER X	29 JUN 22 6:00PM 6:00PM 6:00PM		SIZE D 24355	DRAWING NUMBER 09 - 074836
DO NOT SCALE DWG		SCALE 1/1		SHEET 2 OF 2	